

08-08-02

1763

Attorney Docket No.: NECW 18.159

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Atsushi NISHIZAWA

Serial No.: 09/751,979

Filed: December 29, 2000

Title: **MANUFACTURING METHOD OF SEMICONDUCTOR INTEGRATED CIRCUIT INCLUDING SIMULTANEOUS FORMATION OF VIA HOLE REACHING METAL WIRING AND CONCAVE GROOVE IN INTERLAYER FILM AND SEMICONDUCTOR INTEGRATED CIRCUIT MANUFACTURED WITH THE MANUFACTURING METHOD**

Examiner: George A. Goudreau

Group Art Unit: 1763

Assistant Commission for Patents
Washington, D.C. 20231

TECHNOLOGY CENTER 1700

AUG 12 2002

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CHANGE IN CORRESPONDENCE ADDRESS

SIR :

It is respectfully requested that any future correspondence regarding the above-referenced application be directed to Applicant's attorneys (previously appointed) at the following new correspondence address:

Katten Muchin Zavis Rosenman
575 Madison Avenue
New York, New York 10022
Phone: (212) 940-8800
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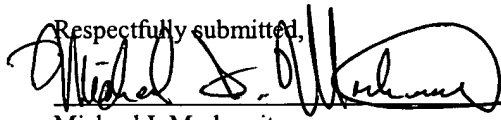
Any inquiries regarding this change in address may be directed to the Applicant's undersigned attorney at the above-referenced telephone numbers.

Our **CUSTOMER NUMBER 026304** remains the same.

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Respectfully submitted,


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